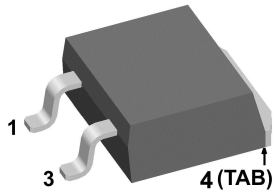
XPT IGBT

V_{CES} = 1200 V
I_{C25} = 38 A
$V_{CE(sat)}$ = 1.8 V

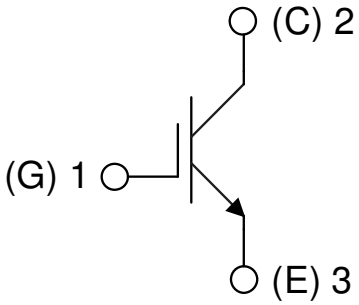
Single IGBT

Part number

IXA20I1200PZ



Backside: collector



Features / Advantages:

- Easy paralleling due to the positive temperature coefficient of the on-state voltage
- Rugged XPT design (Xtreme light Punch Through) results in:
  - short circuit rated for 10 µsec.
  - very low gate charge
  - low EMI
  - square RBSOA @ 3x Ic
- Thin wafer technology combined with the XPT design results in a competitive low VCE(sat)

Applications:

- AC motor drives
- Solar inverter
- Medical equipment
- Uninterruptible power supply
- Air-conditioning systems
- Welding equipment
- Switched-mode and resonant-mode power supplies
- Inductive heating, cookers
- Pumps, Fans

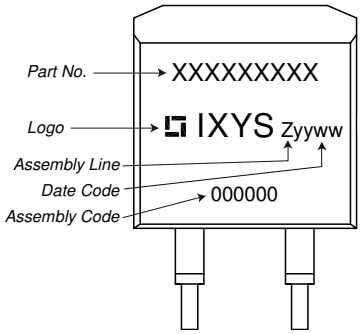
Package: TO-263 (D2Pak-HV)

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0

IGBT				Ratings			
Symbol	**Definition**	**Conditions**		**min.**	**typ.**	**max.**	**Unit**
V_{CES}	*collector emitter voltage*		T_{VJ} = 25°C			1200	V
V_{GES}	*max. DC gate voltage*					±20	V
V_{GEM}	*max. transient gate emitter voltage*					±30	V
I_{C25}	*collector current*		T_C = 25°C			38	A
I_{C80}			T_C = 80°C			22	A
P_{tot}	*total power dissipation*		T_C = 25°C			165	W
$V_{CE(sat)}$	*collector emitter saturation voltage*	I_C = 15 A; V_{GE} = 15 V	T_{VJ} = 25°C		1.8	2.1	V
			T_{VJ} = 125°C		2.1		V
$V_{GE(th)}$	*gate emitter threshold voltage*	I_C = 0.6 mA; V_{GE} = V_{CE}	T_{VJ} = 25°C	5.4	5.9	6.5	V
I_{CES}	*collector emitter leakage current*	V_{CE} = V_{CES}; V_{GE} = 0 V	T_{VJ} = 25°C			0.1	mA
			T_{VJ} = 125°C		0.1		mA
I_{GES}	*gate emitter leakage current*	V_{GE} = ±20 V				500	nA
$Q_{G(on)}$	*total gate charge*	V_{CE} = 600 V; V_{GE} = 15 V; I_C = 15 A			47		nC
$t_{d(on)}$	*turn-on delay time*				48		ns
t_r	*current rise time*	inductive load	T_{VJ} = 125°C		30		ns
$t_{d(off)}$	*turn-off delay time*	V_{CE} = 600 V; I_C = 15 A			230		ns
t_f	*current fall time*	V_{GE} = ±15 V; R_G = 56 Ω			350		ns
E_{on}	*turn-on energy per pulse*				1.6		mJ
E_{off}	*turn-off energy per pulse*				1.7		mJ
RBSOA	*reverse bias safe operating area*	V_{GE} = ±15 V; R_G = 56 Ω	T_{VJ} = 125°C				
I_{CM}		V_{CEmax} = 1200 V				45	A
SCSOA	*short circuit safe operating area*	V_{CEmax} = 1200 V					
t_{SC}	*short circuit duration*	V_{CE} = 900 V; V_{GE} = ±15 V	T_{VJ} = 125°C			10	µs
I_{SC}	*short circuit current*	R_G = 56 Ω; non-repetitive			60		A
R_{thJC}	*thermal resistance junction to case*					0.76	K/W
R_{thCH}	*thermal resistance case to heatsink*				0.25		K/W

Package TO-263 (D2Pak-HV)			Ratings			
Symbol	**Definition**	**Conditions**	**min.**	**typ.**	**max.**	**Unit**
I_{RMS}	*RMS current*	per terminal			35	A
T_{VJ}	*virtual junction temperature*		-40		150	°C
T_{op}	*operation temperature*		-40		125	°C
T_{stg}	*storage temperature*		-40		150	°C
Weight				1.5		g
F_C	*mounting force with clip*		20		60	N
$d_{Spp/App}$	*creepage distance on surface | striking distance through air*	*terminal to terminal*	4.2			mm
$d_{Spb/Apb}$		*terminal to backside*	4.7			mm

Product Marking



Part description

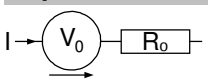
I = IGBT
X = XPT IGBT
A = Gen 1 / std
20 = Current Rating [A]
I = Single IGBT
1200 = Reverse Voltage [V]
PZ = TO-263AB (D2Pak) (2HV)

Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	IXA20I1200PZ	IXA20I1200PZ	Tape & Reel	800	518533

Similar Part	Package	Voltage class
IXA20I1200PZ	TO-220AB (3)	1200
IXA20IF1200HB	TO-247AD (3)	1200

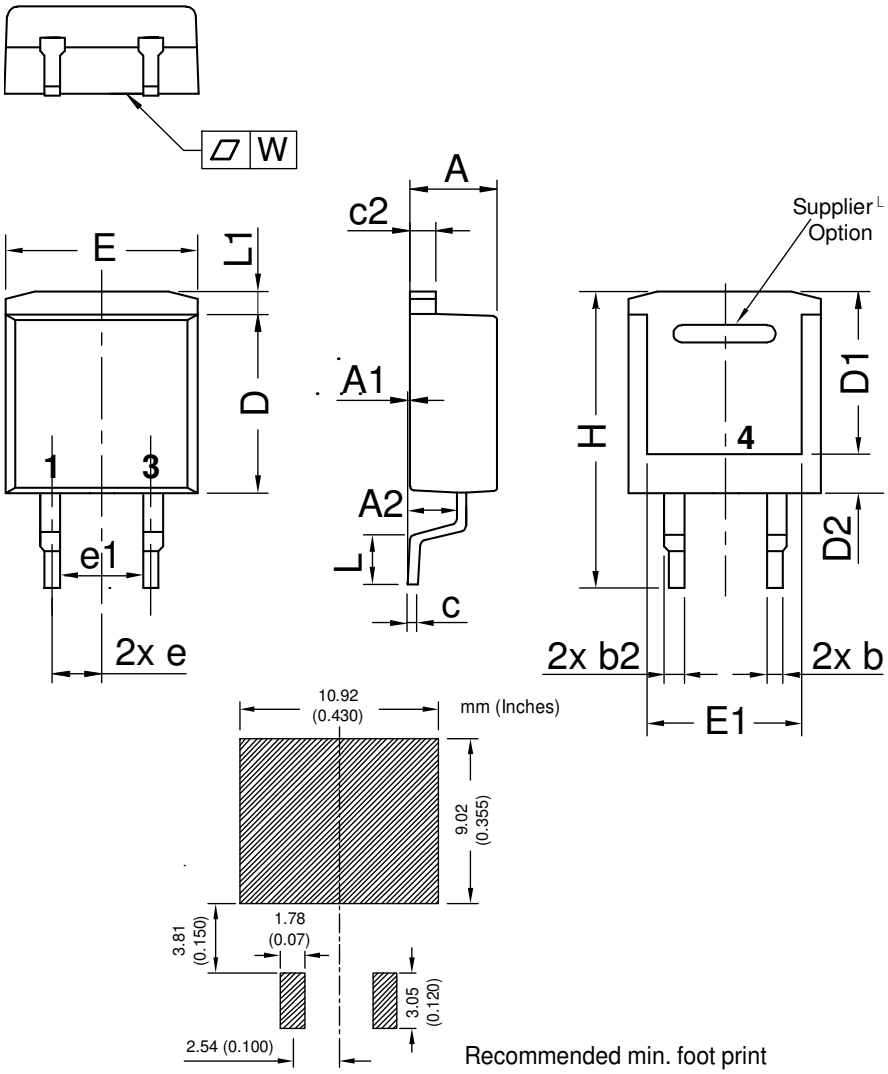
Equivalent Circuits for Simulation

** on die level* T_{VJ} = 150 °C



		IGBT	
$V_{0\,max}$	*threshold voltage*	1.1	V
$R_{0\,max}$	*slope resistance **	86	mΩ

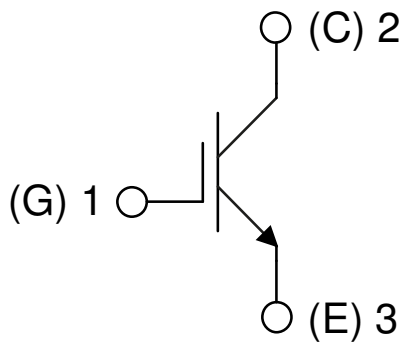
Outlines TO-263 (D2Pak-HV)



Dim.	Millimeter		Inches	
	min	max	min	max
A	4.06	4.83	0.160	0.190
A1	typ. 0.10		typ. 0.004	
A2	2.41		0.095	
b	0.51	0.99	0.020	0.039
b2	1.14	1.40	0.045	0.055
c	0.40	0.74	0.016	0.029
c2	1.14	1.40	0.045	0.055
D	8.38	9.40	0.330	0.370
D1	8.00	8.89	0.315	0.350
D2	2.3		0.091	
E	9.65	10.41	0.380	0.410
E1	6.22	8.50	0.245	0.335
e	2,54 BSC		0,100 BSC	
e1	4.28		0.169	
H	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	1.02	1.68	0.040	0.066
W	typ. 0.02	0.040	typ. 0.0008	0.002

All dimensions conform with and/or within JEDEC standard.

Recommended min. foot print



IGBT

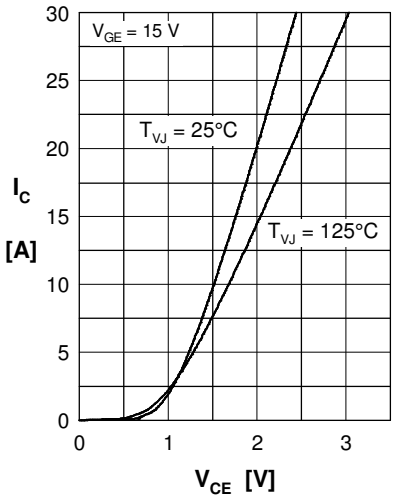


Fig. 1 Typ. output characteristics

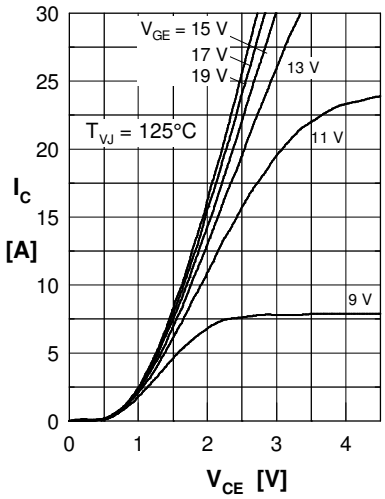


Fig. 2 Typ. output characteristics

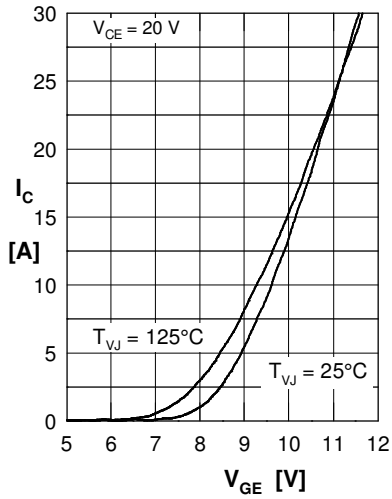


Fig. 3 Typ. transfer characteristics

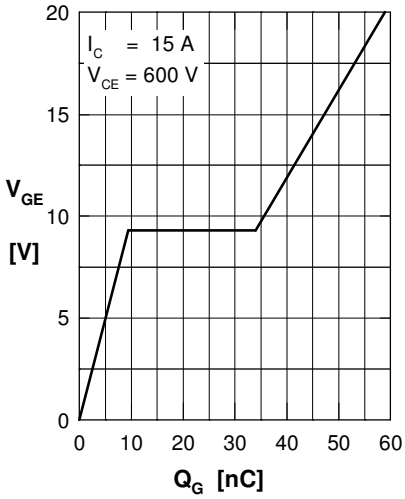


Fig. 4 Typ. turn-on gate charge

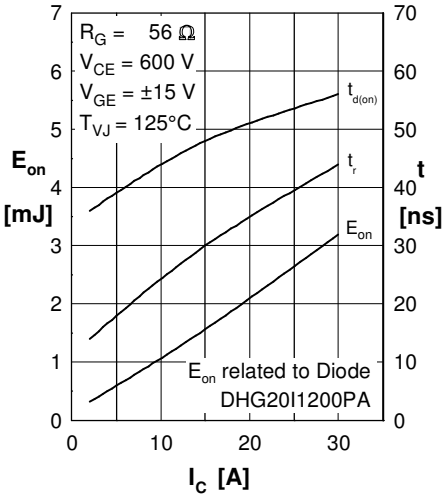


Fig. 5 Typ. switching energy vs. collector current

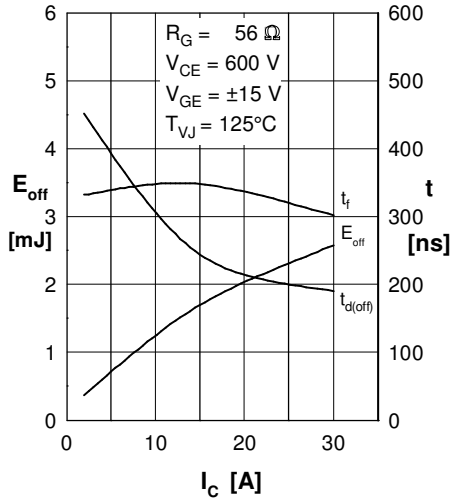


Fig. 6 Typ. switching energy vs. collector current

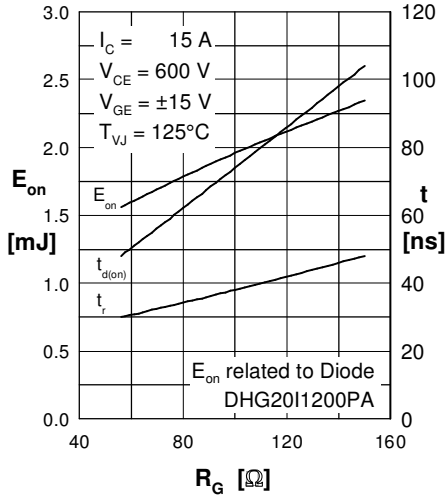


Fig. 7 Typ. switching energy vs. gate resistance

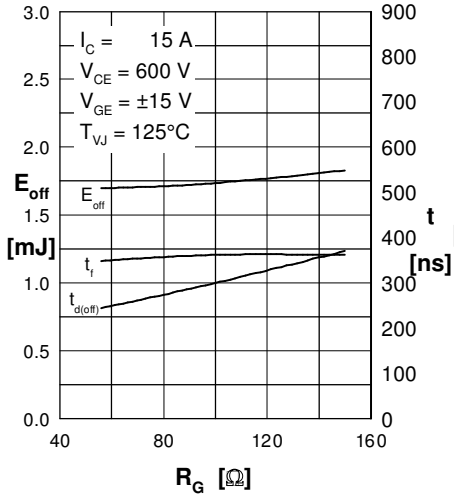


Fig. 8 Typ. switching energy vs. gate resistance

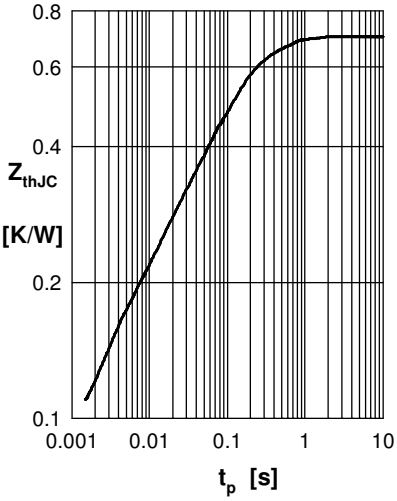


Fig. 9 Typ. transient thermal impedance junction to case